PSMN005-30K

N-channel TrenchMOS SiliconMAX logic level FET

Rev. 01 — 17 November 2009 Product data sheet

1. Product profile

1.1 General description

SiliconMAX logic level N-channel enhancement mode Field-Effect Transistor (FET) in a plastic package using TrenchMOS technology. This product is designed and qualified for use in computing, communications, consumer and industrial applications only.

1.2 Features and benefits

- Low conduction losses due to low on-state resistance
- Suitable for high frequency applications due to fast switching characteristics

1.3 Applications

- Computer motherboards
- DC-to-DC convertors
- Switched-mode power supplies

1.4 Quick reference data

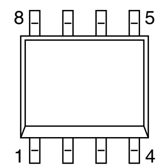
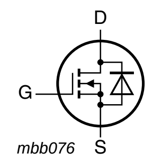
Table 1. Quick reference

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_{DS}	drain-source voltage	$T_j \geq 25$ °C; $T_j \leq 150$ °C	-	-	30	V
I_D	drain current	T_{sp} = 80 °C; V_{GS} = 10 V; see Figure 1	-	-	20	A
P_{tot}	total power dissipation	T_{sp} = 80 °C; see Figure 2	-	-	3.5	W
Dynamic characteristics						
Q_{GD}	gate-drain charge	V_{GS} = 4.5 V; I_D = 20 A; V_{DS} = 15 V; T_j = 25 °C; see Figure 12	-	14	-	nC
Static characteristics						
R_{DSon}	drain-source on-state resistance	V_{GS} = 10 V; I_D = 15 A; T_j = 25 °C; see Figure 10 and 11	-	4.4	5.5	mΩ

founded by Philips

2. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	S	source	 SOT96-1 (SO8)	
2	S	source		
3	S	source		
4	G	gate		
5	D	drain		
6	D	drain		
7	D	drain		
8	D	drain		

3. Ordering information

Table 3. Ordering information

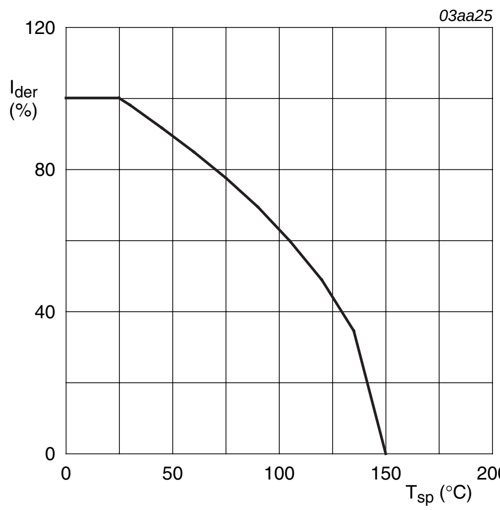
Type number	Package		
	Name	Description	Version
PSMN005-30K	SO8	plastic small outline package; 8 leads; body width 3.9 mm	SOT96-1

4. Limiting values

Table 4. Limiting values

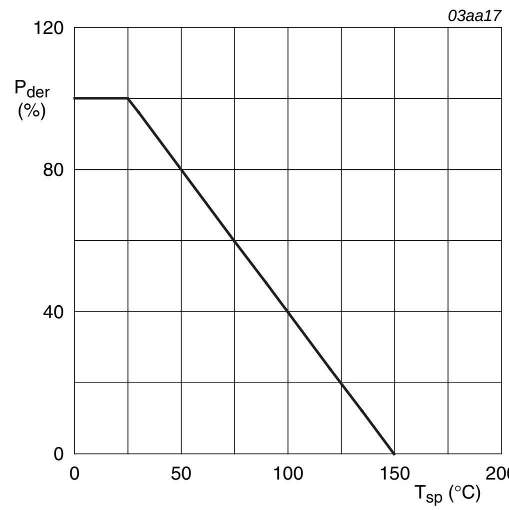
In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V_{DS}	drain-source voltage	$T_j \geq 25$ °C; $T_j \leq 150$ °C	-	30	V
V_{GS}	gate-source voltage		-20	20	V
I_D	drain current	$T_{sp} = 80$ °C; $V_{GS} = 10$ V; see Figure 1	-	20	A
I_{DM}	peak drain current	$T_{sp} = 25$ °C; $t_p \leq 10$ µs; pulsed; see Figure 3	-	60	A
P_{tot}	total power dissipation	$T_{sp} = 80$ °C; see Figure 2	-	3.5	W
T_{stg}	storage temperature		-55	150	°C
T_j	junction temperature		-55	150	°C
Source-drain diode					
I_S	source current	$T_{sp} = 80$ °C	-	20	A
I_{SM}	peak source current	$T_{sp} = 25$ °C; $t_p \leq 10$ µs; pulsed	-	60	A



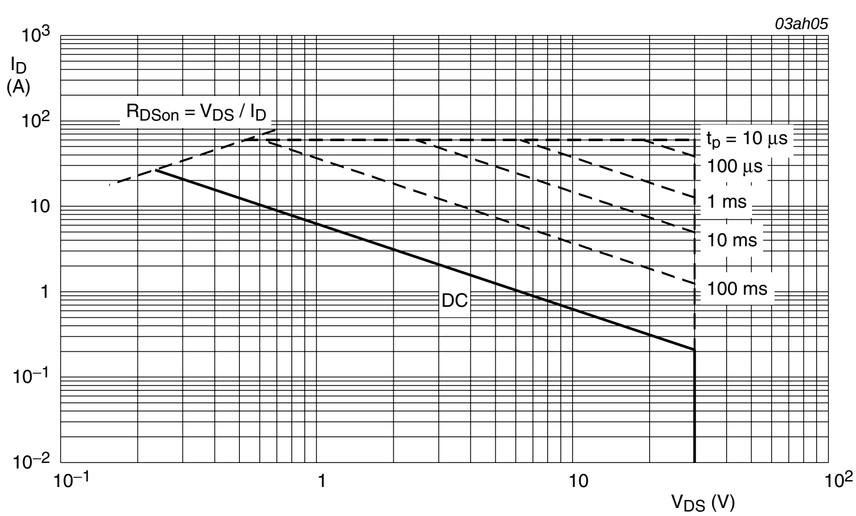
$$I_{der} = \frac{I_D}{I_{D(25°C)}} \times 100\,\%$$

Fig 1. Normalized continuous drain current as a function of solder point temperature



$$P_{der} = \frac{P_{tot}}{P_{tot(25°C)}} \times 100\,\%$$

Fig 2. Normalized total power dissipation as a function of solder point temperature



$T_{SP} = 25°C; I_{DM}$ is single pulse

Fig 3. Safe operating area; continuous and peak drain currents as a function of drain-source voltage

5. Thermal characteristics

Table 5. Thermal characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$R_{th(j-sp)}$	thermal resistance from junction to solder point	mounted on a metal clad board; see Figure 4	-	-	20	K/W

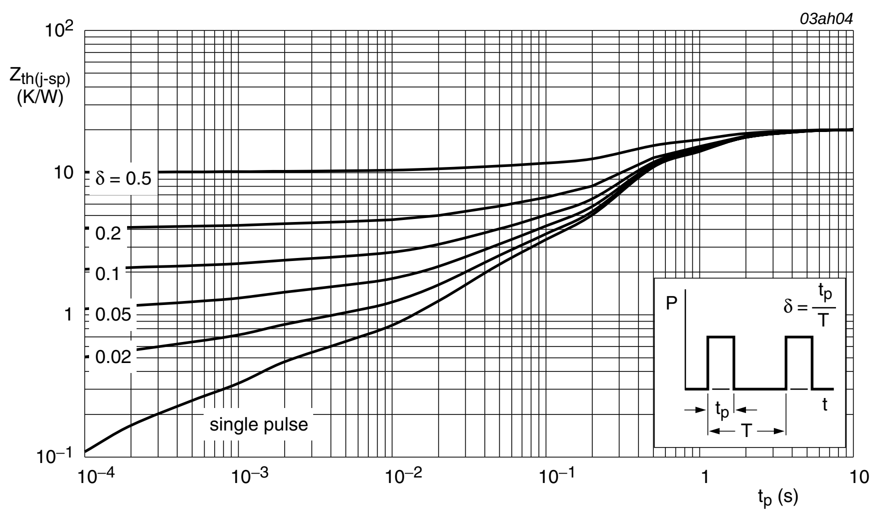
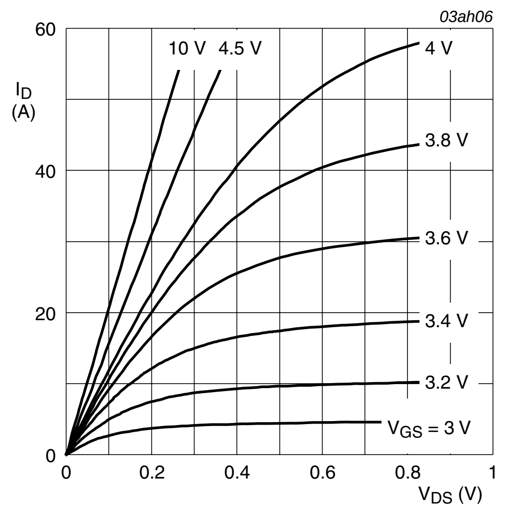


Fig 4. Transient thermal impedance from junction to mounting base as a function of pulse duration

6. Characteristics

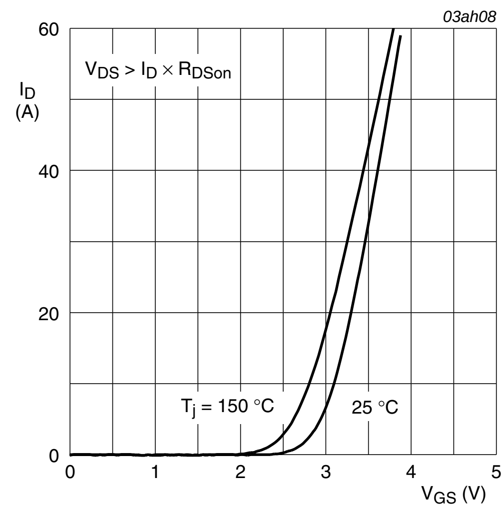
Table 6. Characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Static characteristics						
$V_{(BR)DSS}$	drain-source breakdown voltage	I_D = 250 µA; V_{GS} = 0 V; T_j = 25 °C	30	-	-	V
$V_{GS(th)}$	gate-source threshold voltage	I_D = 1 mA; V_{DS} = V_{GS}; T_j = 150 °C; see Figure 9	0.5	-	-	V
		I_D = 1 mA; V_{DS} = V_{GS}; T_j = -55 °C; see Figure 9	-	-	3.4	V
		I_D = 1 mA; V_{DS} = V_{GS}; T_j = 25 °C; see Figure 9	1	-	3	V
I_{DSS}	drain leakage current	V_{DS} = 30 V; V_{GS} = 0 V; T_j = 25 °C	-	-	1	µA
		V_{DS} = 30 V; V_{GS} = 0 V; T_j = 150 °C	-	-	0.5	mA
I_{GSS}	gate leakage current	V_{GS} = 20 V; V_{DS} = 0 V; T_j = 25 °C	-	-	100	nA
		V_{GS} = -20 V; V_{DS} = 0 V; T_j = 25 °C	-	-	100	nA
R_{DSon}	drain-source on-state resistance	V_{GS} = 4.5 V; I_D = 13 A; T_j = 25 °C; see Figure 10 and 11	-	6.6	8	mΩ
		V_{GS} = 10 V; I_D = 15 A; T_j = 25 °C; see Figure 10 and 11	-	4.4	5.5	mΩ
Dynamic characteristics						
$Q_{G(tot)}$	total gate charge	I_D = 20 A; V_{DS} = 15 V; V_{GS} = 4.5 V; T_j = 25 °C; see Figure 12	-	34	-	nC
Q_{GS}	gate-source charge		-	15	-	nC
Q_{GD}	gate-drain charge		-	14	-	nC
C_{iss}	input capacitance	V_{DS} = 25 V; V_{GS} = 0 V; f = 1 MHz; T_j = 25 °C; see Figure 13	-	3100	-	pF
C_{oss}	output capacitance		-	605	-	pF
C_{rss}	reverse transfer capacitance		-	405	-	pF
$t_{d(on)}$	turn-on delay time	V_{DS} = 15 V; R_L = 15 Ω; V_{GS} = 10 V; $R_{G(ext)}$ = 6 Ω; T_j = 25 °C	-	18	-	ns
t_r	rise time		-	16	-	ns
$t_{d(off)}$	turn-off delay time		-	65	-	ns
t_f	fall time		-	45	-	ns
g_{fs}	transfer conductance	V_{DS} = 15 V; I_D = 20 A; T_j = 25 °C	-	60	-	S
Source-drain diode						
V_{SD}	source-drain voltage	I_S = 15 A; V_{GS} = 0 V; T_j = 25 °C; see Figure 14	-	0.81	1.3	V
t_{rr}	reverse recovery time	I_S = 10 A; dI_S/dt = -100 A/µs; V_{GS} = 0 V; V_{DS} = 25 V; T_j = 25 °C	-	35	-	ns
Q_r	recovered charge		-	20	-	nC



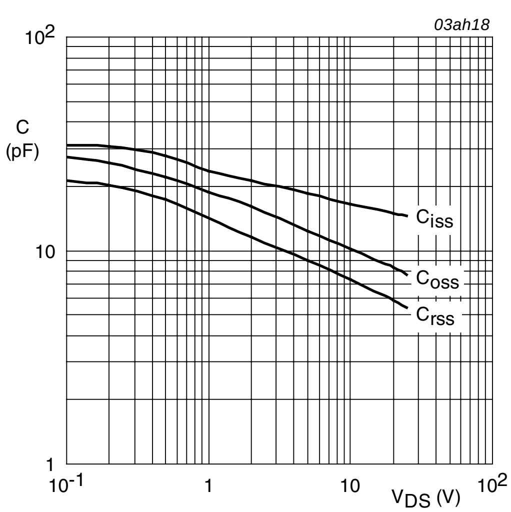
$T_j = 25°C$

Fig 5. Output characteristics: drain current as a function of drain-source voltage; typical values



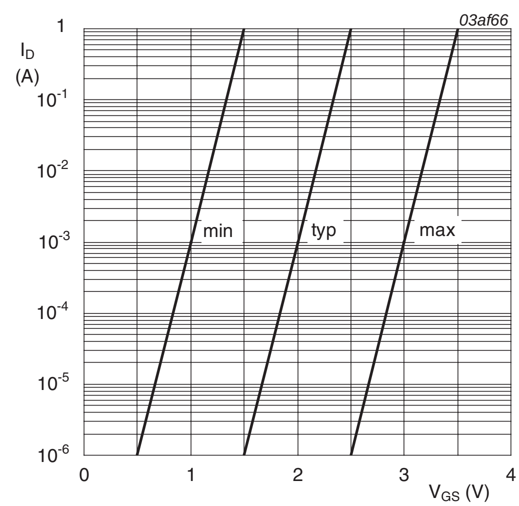
$T_j = 25°C \text{ and } 175°C; V_{DS} > I_D \times R_{DSon}$

Fig 6. Transfer characteristics: drain current as a function of gate-source voltage; typical values



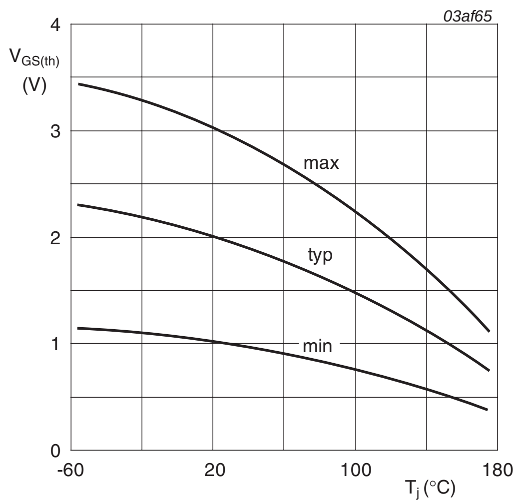
$V_{GS} = 0V; f = 1MHz$

Fig 7. Input, output and reverse transfer capacitances as a function of drain-source voltage; typical values



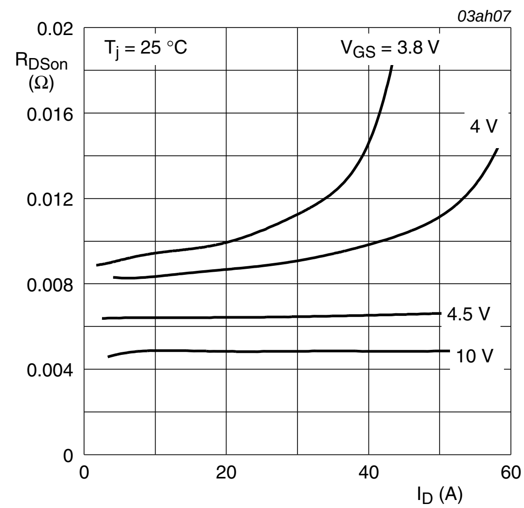
$T_j = 25°C; V_{DS} = 5V$

Fig 8. Sub-threshold drain current as a function of gate-source voltage



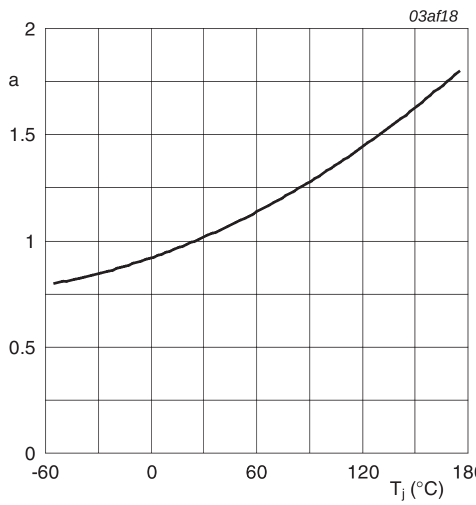
$I_D = 1mA; V_{DS} = V_{GS}$

Fig 9. Gate-source threshold voltage as a function of junction temperature



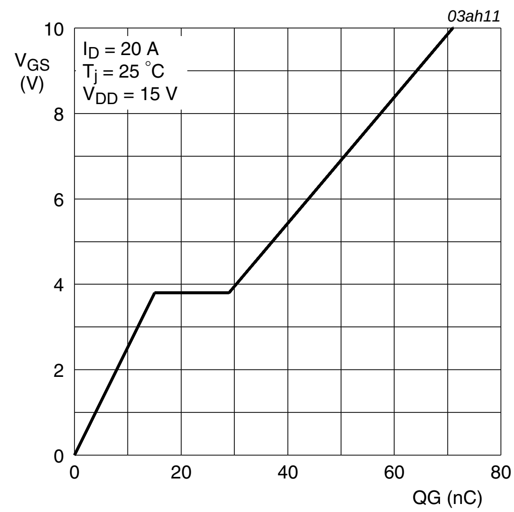
$T_j = 25°C$

Fig 10. Drain-source on-state resistance as a function of drain current; typical values



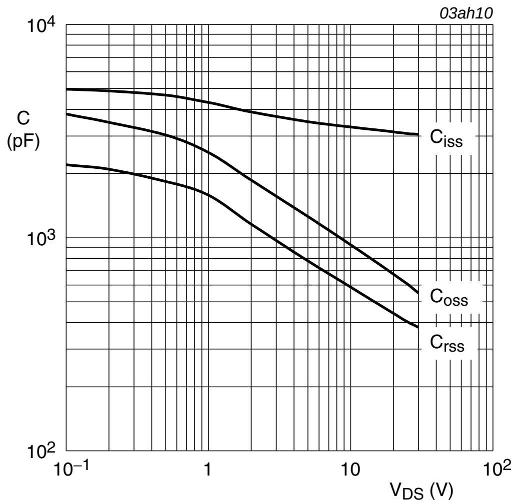
$$a = \frac{R_{DSon}}{R_{DSon(25°C)}}$$

Fig 11. Normalized drain-source on-state resistance factor as a function of junction temperature



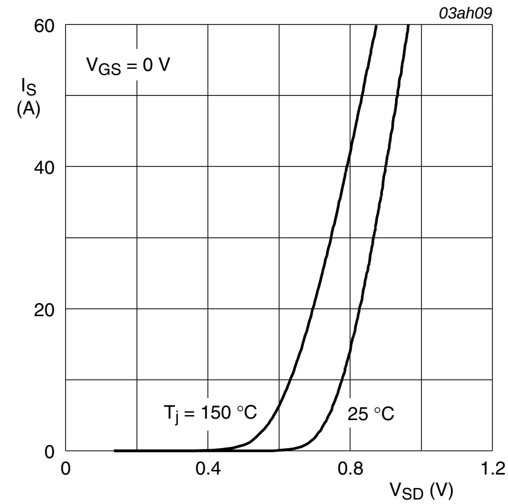
$I_D = 20A; V_{DS} = 15V$

Fig 12. Gate-source voltage as a function of gate charge; typical values



$V_{GS} = 0V; f = 1MHz$

Fig 13. Input, output and reverse transfer capacitances as a function of drain-source voltage; typical values

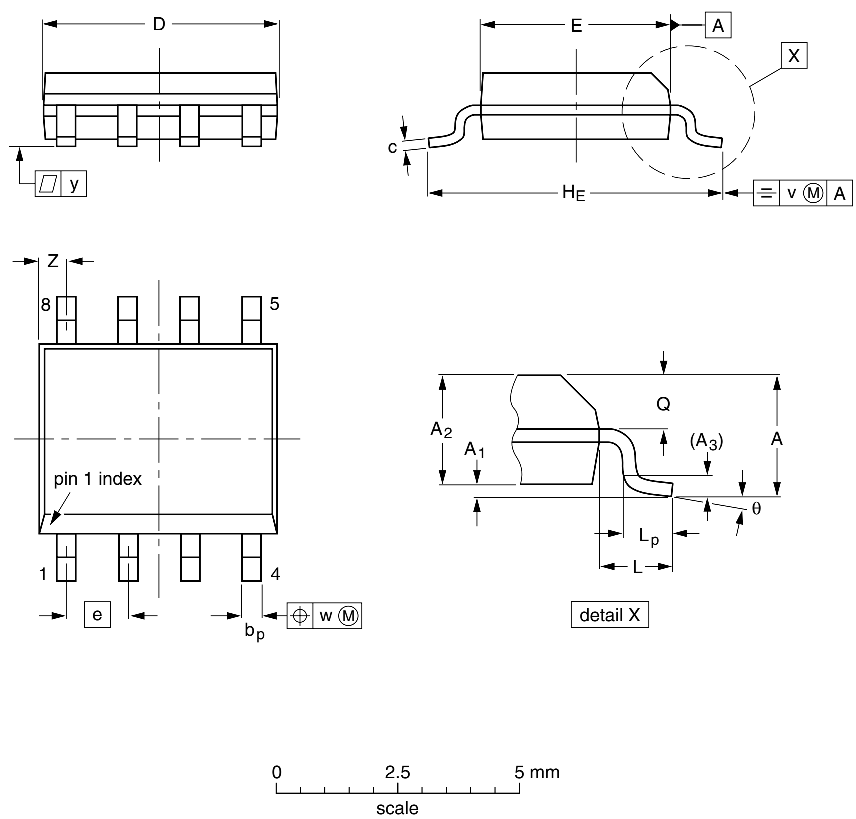


$T_j = 25°C \text{ and } 175°C; V_{GS} = 0V$

Fig 14. Source current as a function of source-drain voltage; typical values

7. Package outline

SO8: plastic small outline package; 8 leads; body width 3.9 mm **SOT96-1**



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A_1	A_2	A_3	b_p	c	D(1)	E(2)	e	H_E	L	L_p	Q	v	w	y	Z(1)	θ
mm	1.75	0.25 0.10	1.45 1.25	0.25	0.49 0.36	0.25 0.19	5.0 4.8	4.0 3.8	1.27	6.2 5.8	1.05	1.0 0.4	0.7 0.6	0.25	0.25	0.1	0.7 0.3	8° 0°
inches	0.069	0.010 0.004	0.057 0.049	0.01	0.019 0.014	0.0100 0.0075	0.20 0.19	0.16 0.15	0.05	0.244 0.228	0.041	0.039 0.016	0.028 0.024	0.01	0.01	0.004	0.028 0.012	

Notes

1. Plastic or metal protrusions of 0.15 mm (0.006 inch) maximum per side are not included.
2. Plastic or metal protrusions of 0.25 mm (0.01 inch) maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT96-1	076E03	MS-012				~~99-12-27~~ 03-02-18

Fig 15. Package outline SOT96-1 (SO8)

8. Revision history

Table 7. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
PSMN005-30K_1	20091117	Product data sheet	-	-

9. Legal information

9.1 Data sheet status

Document status [1][2]	Product status[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL http://www.nxp.com.

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11. Contents

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